

77. (New) A transferable thermal interface having:

an encapsulant and a plurality of thermally conductive fibers forming a thermally conductive composite; and

individual fibers having a length and the encapsulant having a thickness encapsulating a portion of the individual lengths of the plurality of fibers;

wherein the improvement comprises a release liner, the thermally conductive composite being over the release liner and the fibers extending downwardly to contact the release liner.

78. (New) The interface of claim 77 wherein an average length of the fibers is greater than an average thickness of the encapsulant along an average direction of the fiber lengths, the improvement further comprising the thermally conductive composite including such encapsulant being over the release liner.

79. (New) The interface of claim 77 wherein the encapsulant includes a gel, the improvement further comprising the thermally conductive composite including gel being over the release liner.

80. (New) The interface of claim 77 wherein the composite further includes:

the fibers embedded in a support material having a first surface and a second opposing surface, the fiber portions extending upwardly out of the second opposing surface;

the encapsulant between the fiber portions and over the support material; and

a third surface defining an outermost surface of the thermally conductive composite except for the fibers terminating in tips that are elevationally above the third surface and the encapsulant;

wherein the improvement further comprises the support material being on the release liner.

81. (New) The interface of claim 77 wherein the thermally conductive composite further includes a support material and wherein the improvement further comprises the support material being on the release liner, the encapsulant being on the support material, and the fibers being in the support material.

82. (New) The interface of claim 77 wherein the improvement further comprises the release liner comprising a silicone coated sheet.

83. (New) The interface of claim 77 wherein the improvement further comprises the release liner having a thickness less than 0.005 inches.

84. (New) The interface of claim 77 wherein the improvement further comprises the release liner being electrically conductive.

85. (New) The interface of claim 77 wherein the improvement further comprises another release liner over the encapsulant and fibers.

86. (New) A transferable thermal interface having:

an encapsulant and a plurality of thermally conductive fibers forming a thermally conductive composite; and

individual fibers having a length and the encapsulant having a thickness encapsulating a portion of the individual lengths of the plurality of fibers;

wherein the improvement comprises a release liner having a thickness less than 0.005 inches, the thermally conductive composite being over the release liner.

87. (New) The interface of claim 86 wherein an average length of the fibers is greater than an average thickness of the encapsulant along an average direction of the fiber lengths, the improvement further comprising the thermally conductive composite including such encapsulant being over the release liner.

88. (New) The interface of claim 86 wherein the encapsulant includes a gel, the improvement further comprising the thermally conductive composite including gel being over the release liner.

89. (New) The interface of claim 86 wherein the composite further includes:

the fibers embedded in a support material having a first surface and a second opposing surface, the fiber portions extending upwardly out of the second opposing surface;

the encapsulant between the fiber portions and over the support material; and

a third surface defining an outermost surface of the thermally conductive composite except for the fibers terminating in tips that are elevationally above the third surface and the encapsulant;

wherein the improvement further comprises the support material being on the release liner.

90. (New) The interface of claim 89 wherein the improvement further comprises the fibers extending downwardly to at or below the first surface of the support material.

91. (New) The interface of claim 86 wherein the thermally conductive composite further includes a support material and wherein the improvement further comprises the support material being on the release liner, the encapsulant being on the support material, and the fibers being in the support material.

92. (New) The interface of claim 86 wherein the improvement further comprises the release liner comprising a silicone coated sheet.

93. (New) The interface of claim 86 wherein the improvement further comprises the release liner being electrically conductive.

94. (New) The interface of claim 86 wherein the improvement further comprises another release liner over the encapsulant and fibers.

95. (New) A transferable thermal interface having:

an encapsulant and a plurality of thermally conductive fibers forming a thermally conductive composite; and

individual fibers having a length and the encapsulant having a thickness encapsulating a portion of the individual lengths of the plurality of fibers;

wherein the improvement comprises an electrically conductive release liner, the thermally conductive composite being over the release liner.

96. (New) The interface of claim 95 wherein an average length of the fibers is greater than an average thickness of the encapsulant along an average direction of the fiber lengths, the improvement further comprising the thermally conductive composite including such encapsulant being over the release liner.

97. (New) The interface of claim 95 wherein the encapsulant includes a gel, the improvement further comprising the thermally conductive composite including gel being over the release liner.

98. (New) The interface of claim 95 wherein the composite further includes:

the fibers embedded in a support material having a first surface and a second opposing surface, the fiber portions extending upwardly out of the second opposing surface;

the encapsulant between the fiber portions and over the support material; and

a third surface defining an outermost surface of the thermally conductive composite except for the fibers terminating in tips that are elevationally above the third surface and the encapsulant;

wherein the improvement further comprises the support material being on the release liner.

99. (New) The interface of claim 98 wherein the improvement further comprises the fibers extending downwardly to at or below the first surface of the support material.

100. (New) The interface of claim 95 wherein the thermally conductive composite further includes a support material and wherein the improvement further comprises the support material being on the release liner, the encapsulant being on the support material, and the fibers being in the support material.

101. (New) The interface of claim 95 wherein the improvement further comprises the release liner comprising a silicone coated sheet.

102. (New) The interface of claim 95 wherein the improvement further comprises another release liner over the encapsulant and fibers.